

## Ultra Light-Weld® 3094 Low-Stress Plastic Bonder

**APPLICATIONS**

- Sign Assembly
- Plastic Assembly
- Household Appliance Assembly

**FEATURES**

- UV/Visible Light Cure
- Fast Curing
- Different Viscosities Available
- Low Shrinkage & Stress

**RECOMMENDED SUBSTRATES**

- PMMA
- PC
- PU
- PS

DYMAX Ultra Light-Weld® 3094 is designed for rapid bonding and sealing of a variety of plastics. DYMAX Ultra Light-Weld® materials contain no nonreactive solvents and cure upon exposure to light. Their ability to cure in seconds enables faster processing, greater output, and lower processing costs. When cured with DYMAX light-curing spot lamps, focused-beam lamps, or flood lamps, they deliver optimum speed and performance for plastics assembly. DYMAX lamps offer the optimum balance of UV and visible light for the fastest, deepest cures. This product is in full compliance with the RoHS Directives 2002/95/EC and 2003/11EC.

UNCURED PROPERTIES *		
Property	Value	Test Method
Solvent Content	No Nonreactive Solvents	N/A
Chemical Class	Acrylated Urethane	N/A
Appearance	Light Yellow Translucent Liquid - Gel	N/A
Soluble in	Organic Solvents	N/A
Density, g/ml	1.01 – 1.03	ASTM D1875
Viscosity, cP (20 rpm)	1,000 cP	ASTM D1084

CURED MECHANICAL PROPERTIES *		
Property	Value	Test Method
Durometer Hardness	D62	ASTM D2240
Tensile at Break, MPa [psi]	14 [2,100]	ASTM D638
Elongation at Break, %	170	ASTM D638
Modulus of Elasticity, MPa [psi]	240 [35,000]	ASTM D638

OTHER CURED PROPERTIES *		
Property	Value	Test Method
Refractive Index (20°C)	1.5	ASTM D542
Boiling Water Absorption, % (2 hr)	7.2	ASTM D570
Water Absorption, % (25°C, 24 hr)	22	ASTM D570
Linear Shrinkage, %	0.2	ASTM D2566

\* Not Specifications  
N/A Not Applicable

ADHESION	
Substrate	Recommendation
ABS acrylonitrile-butadiene-styrene	o
PA polyamide	o
PC polycarbonate	✓
PC/PCTG Blend blend of PC and PCTG	o
PCTG poly(cyclohexylene dimethylene terephthalate)glycol	o
PET poly(ethylene terephthalate)	o
PETG poly(ethylene terephthalate)glycol	o
PI polyimide	o
PMMA poly(methyl methacrylate)	✓
PS polystyrene	✓
PSU polysulfone	o
PU polyurethane	✓
PVC poly(vinyl chloride)	o
SAN styrene-acrylonitrile	✓
Glass: borosilicate, quartz, mica	o
SS: stainless steel	o

✓ Recommended Adhesive    o Limited Applications  
st Requires Surface Treatment (e.g. plasma, corona treatment, etc.)



**CURING GUIDELINES**

Fixture time is defined as the time to develop a shear strength of 0.1 N/mm<sup>2</sup> [10 psi] between glass slides. Actual cure time typically is 3 to 5 times fixture time.

DYMAX Curing System (Intensity)	Fixture Time or Belt Speed <sup>B</sup>
2000-EC (50 mW/cm <sup>2</sup> ) <sup>A</sup>	<1 sec
5000-EC (200 mW/cm <sup>2</sup> ) <sup>A</sup>	<1 sec
BlueWave <sup>®</sup> 75 (5.0 W/cm <sup>2</sup> ) <sup>A</sup>	<0.2 sec
BlueWave <sup>®</sup> 200 (10 W/cm <sup>2</sup> ) <sup>A</sup>	<0.2 sec
UVCS Conveyor with one 5000-EC (200 mW/cm <sup>2</sup> ) <sup>C</sup>	>8.2 m/min >27 [ft/min]
UVCS Conveyor with Fusion F300S (2.5 W/cm <sup>2</sup> ) <sup>C</sup>	>8.2 m/min >27 [ft/min]

**A** Intensity was measured over the UVA range (320-395 nm) using a DYMAX ACCU-CAL™ 50 Radiometer.

**B** Curing through light-blocking substrates may require longer cure times if they obstruct wavelengths used for light curing (320-400 nm for UV light curing, 320-450 nm for UV/Visible light curing). These fixture times/belt speeds are typical for curing thin films through 100% light-transmitting substrates.

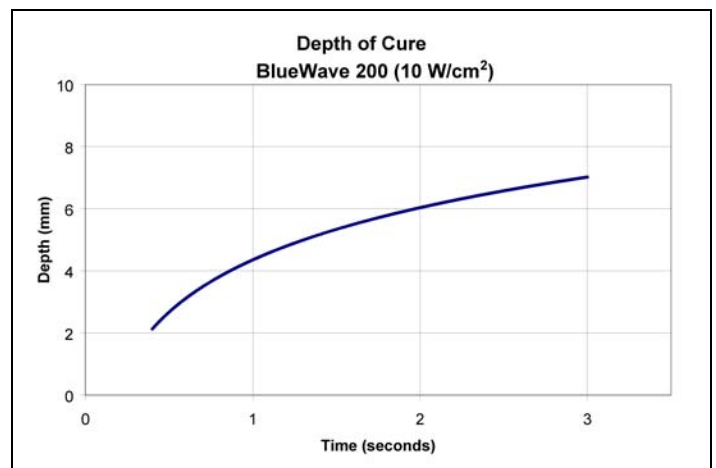
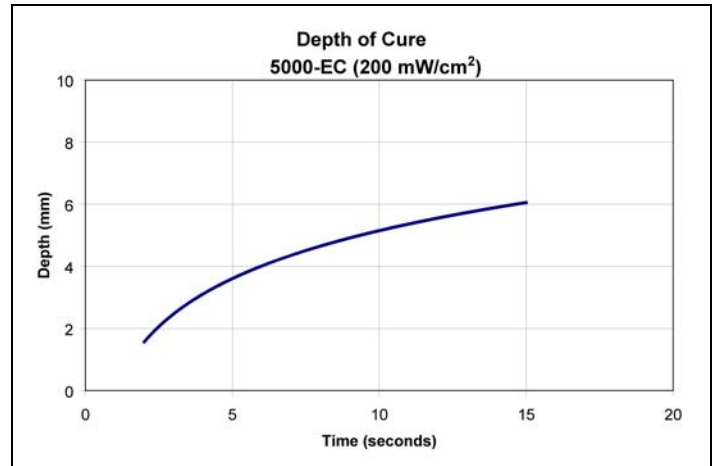
**C** At 53 mm [2.1 in] focal distance. Maximum speed of conveyor is 8.2 m/min [27 ft/min]. Intensity was measured over the UVA range (320-395 nm) using the DYMAX ACCU-CAL™ 100 Radiometer.

Full cure is best determined empirically by curing at different times and intensities, and measuring the corresponding change in cured properties such as tackiness, adhesion, hardness, etc. Full cure is defined as the point at which more light exposure no longer improves cured properties. Higher intensities or longer cures (up to 5x) generally will not degrade DYMAX light-curable adhesives.

DYMAX recommends that customers employ a safety factor by curing longer and/or at higher intensities than required for full cure. Although DYMAX Applications Engineering can provide technical support and assist with process development, each customer ultimately must determine and qualify the appropriate curing parameters required for their unique application.

**DEPTH OF CURE**

The graphs below show the increase in depth of cure as a function of exposure time with two different lamps at different intensities. A 9.5 mm [0.37 in] diameter specimen was cured in a polypropylene mold and cooled to room temperature. It was then released from the mold and the cure depth was measured.



**OPTIMIZING PERFORMANCE AND HANDLING**

1. This product cures with exposure to UV and visible light. Exposure to ambient and artificial light should be kept to a minimum before curing. Dispensing components including needles and fluid lines should be 100% light blocking, not just UV blocking.
2. All bond surfaces should be clean and free from grease, mold release, or other contaminants prior to dispensing the adhesive.
3. Cure speed is dependent upon many variables, including lamp intensity, distance from the light source, required depth of cure, bond gap, and percent light transmission of the substrate.
4. Oxygen in the atmosphere may inhibit surface cure. Surfaces exposed to air may require high-intensity (>100 mW/cm<sup>2</sup>) UV light to produce a dry surface cure. Flooding the bond area with an inert gas, such as nitrogen, can also reduce the affects of oxygen inhibition.
5. Parts should be allowed to cool after cure before testing and subjecting to any loads.
6. In rare cases, stress cracking may occur in assembled parts. Three options may be explored to eliminate this problem. One option is to heat anneal the parts to remove molded-in stresses. A second option is to open the gap between mating parts to reduce stress caused by an interference fit. The third option is to minimize the amount of time the liquid adhesive remains in contact with the substrate(s) prior to curing.
7. Light curing generally produces some heat. If necessary, cooling fans can be placed in the curing area to reduce the heating effect on components.
8. At the point of curing, an air exhaust system is recommended to dissipate any heat and vapors formed during the curing process.

**DISPENSING THE ADHESIVE**

This material may be dispensed with a variety of manual and automatic applicators or other equipment as required. Questions relating to dispensing and curing systems for specific applications should be referred to DYMEX Applications Engineering.

**CLEAN UP**

Uncured material may be removed from dispensing components and parts with organic solvents. Cured material will be impervious to many solvents and difficult to remove. Clean up of cured material may require mechanical methods of removal.

**PERFORMANCE AFTER TEMPERATURE EXPOSURE**

Light-cured DYMEX materials typically have a lower thermal limit of -54°C [-65°F] and an upper limit of 150°C [300°F]. Many DYMEX products can withstand temperatures outside of this range for short periods of time. Please contact DYMEX Applications Engineering for assistance.

**STORAGE AND SHELF LIFE**

Store the material in a cool, dark place when not in use. Do not expose to light. This product may polymerize upon prolonged exposure to ambient and artificial light. Keep covered when not in use. This material has a minimum 12-month shelf life from date of shipment, unless otherwise specified, when stored between 10°C [50°F] and 32°C [90°F] in the original, unopened container.

**GENERAL INFORMATION**

This product is intended for industrial use only. Keep out of the reach of children. Avoid breathing vapors. Avoid contact with skin, eyes, and clothing. Wear impervious gloves. Repeated or continuous skin contact with uncured material may cause irritation. Remove material from skin with soap and water. Never use organic solvents to remove material from skin and eyes. For more information on the safe handling of this material, please refer to the Material Safety Data Sheet before use.

**RECOMMENDED DYMEX LITERATURE**

LIT010A	Guide to Selecting and Using UV Light-Curing Systems
LIT077	Chemical Safety
LIT133	UV Light-Curing System Safety Considerations
LIT159	ACCU-CAL™ 50 Radiometer
LIT206	Flood and Focused-Beam UV Light-Curing Systems
LIT218	BlueWave® 200 UV Light-Curing Spot Lamp
LIT249	Industrial Assembly Adhesives Guide

Literature is available through our website [www.dymax.com](http://www.dymax.com), or by calling any DYMEX location.

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